

28. (New) The substrate of Claim 27, wherein the integrated circuit forms part of the security thread.

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Cont. 29. (New) The substrate of Claim 27, wherein the security thread has a thickness of 5-60% of the thickness of the substrate.

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#### SUPPORT FOR THE AMENDMENTS

New Claims 27-29 are supported by originally filed Claims 1 and 5-7. No new matter is believed to be added by entry of these amendments. Claims 1-4 and 8-29 are active.

#### REMARKS

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Applicants would like to thank Examiner Fureman for the helpful and courteous discussion held with Applicants' representative on March 26, 2003. During the discussion it was noted that neither Haghiri nor Brown expressly describe flexible circuits, and provide examples only of "rigid" circuits prepared on a silicon wafer. Furthermore, it was noted that circuits comprising a semiconductive polymer, or circuits printed on flexible substrates are not necessarily flexible.

The rejections of the claims under 35 U.S.C. § 103(a) over the combination of Haghiri, Brown, the present specification at page 7, line 31 to page 8, line 15, Giustiniani, Bratchley, and Uetani are respectfully traversed. None of the applied references in combination suggest the claimed substrate.

The claimed substrate is made from paper, and has at least one flexible integrated circuit comprising a semiconductive organic polymer. Thus, in one embodiment, a flexible integrated circuit may be incorporated into a security paper, such as bank notes, passports, identity cards, and securities (present specification at page 7, lines 7-10). Conventional rigid integrated circuits are not as suitable for flexible paper substrates, because rigid integrated